

**RoHS** 

COMPLIANT HALOGEN

FREE Available

# FW705-TL-E-VB Datasheet Dual P-Channel 20V (D-S) MOSFET

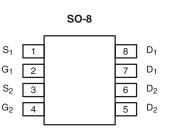
| PRODUCT SUMMARY     |                                    |                    |  |  |
|---------------------|------------------------------------|--------------------|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)            | I <sub>D</sub> (A) |  |  |
|                     | 0.018 at V <sub>GS</sub> = - 4.5 V | - 8.9              |  |  |
| - 20                | 0.022 at V <sub>GS</sub> = - 2.5 V | - 8.1              |  |  |
|                     | 0.030 at V <sub>GS</sub> = - 1.8 V | - 3.6              |  |  |

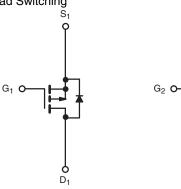
#### FEATURES

- Halogen-free According to IEC 61249-2-21
   Definition
- Trench Power MOSFET
- Advanced High Cell Density Process
- Compliant to RoHS Directive 2002/95/EC

#### APPLICATIONS

Load Switching







S<sub>2</sub>

P-Channel MOSFET

P-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \degree C$ , unless otherwise noted |                        |                                   |        |              |      |
|---|------------------------|-----------------------------------|--------|--------------|------|
| Parameter   |                        | Symbol                            | 10 s   | Steady State | Unit |
| Drain-Source Voltage  |                        | V <sub>DS</sub>                   | - 20   |              | V    |
| Gate-Source Voltage   |                        | V <sub>GS</sub>                   | ± 12   |              | v    |
|   | T <sub>A</sub> = 25 °C | – I <sub>D</sub>                  | - 8.9  | - 6.7        |      |
| Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>               | T <sub>A</sub> = 70 °C |                                   | - 7.1  | - 5.4        |      |
| Pulsed Drain Current  |                        | I <sub>DM</sub>                   | - 30   |              | A    |
| Continuous Source Current (Diode Conduction) <sup>a</sup>                     |                        | ۱ <sub>S</sub>                    | - 1.7  | - 0.9        |      |
|   | T <sub>A</sub> = 25 °C | PD                                | 2.0    | 1.1          | w    |
| Maximum Power Dissipation <sup>a</sup>  | T <sub>A</sub> = 70 °C | ۲D                                | 1.3    | 0.7          | VV I |
| Operating Junction and Storage Temperature Range                              |                        | T <sub>J</sub> , T <sub>stg</sub> | - 55 t | to 150       | °C   |

| THERMAL RESISTANCE RATINGS               |              |                     |         |         |      |
|--|--------------|---------------------|---------|---------|------|
| Parameter                                |              | Symbol              | Typical | Maximum | Unit |
| Manimum hundling to Angleing 18          | t ≤ 10 s     | - R <sub>thJA</sub> | 46      | 62.5    | °C/W |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State |                     | 80      | 110     |      |
| Maximum Junction-to-Foot (Drain)         | Steady State | R <sub>thJF</sub>   | 24      | 32      |      |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

| Parameter                                     | Symbol              | Test Conditions   | Min.  | Тур.  | Max.  | Unit |  |
|---|---------------------|---|-------|-------|-------|------|--|
| Static  |                     |   |       |       |       |      |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | $V_{DS} = V_{GS}, I_D = -350 \ \mu A$ - 0.                |       |       | - 1.0 | ۷    |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>    | $V_{DS} = 0 V, V_{GS} = \pm 8 V$                          |       |       | ± 100 | nA   |  |
| Zero Gate Voltage Drain Current               | 1                   | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V           |       |       | - 1   | μA   |  |
|   | IDSS                | $V_{DS}$ = - 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C        |       |       | - 5   |      |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>  | V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 4.5 V        | - 30  |       |       | А    |  |
|   |                     | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 8.9 A       |       | 0.018 |       |      |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub> | V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 8.1 A       | 0.022 |       |       | Ω    |  |
|   |                     | V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 3.6 A       |       | 0.030 |       |      |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>     | V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 8.9 A        |       | 26    |       | S    |  |
| Diode Forward Voltage <sup>a</sup>            | V <sub>SD</sub>     | I <sub>S</sub> = - 1.7 A, V <sub>GS</sub> = 0 V           |       | - 0.7 | - 1.2 | V    |  |
| Dynamic <sup>b</sup>                          | •                   |   |       | •     |       |      |  |
| Total Gate Charge                             | Qg                  |   |       | 34.5  | 52    |      |  |
| Gate-Source Charge                            | Q <sub>gs</sub>     | $V_{DS}$ = - 10 V, $V_{GS}$ = - 4.5 V, $I_D$ = - 8.9 A    |       | 5.1   |       | nC   |  |
| Gate-Drain Charge                             | Q <sub>gd</sub>     |   |       | 9.6   |       |      |  |
| Gate Resistance                               | Rg                  |   |       | 9     |       | Ω    |  |
| Turn-On Delay Time                            | t <sub>d(on)</sub>  |   |       | 25    | 40    |      |  |
| Rise Time                                     | t <sub>r</sub>      | $V_{DD}$ = - 10 V, $R_L$ = 6 $\Omega$                     |       | 46    | 70    |      |  |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> | $I_D\cong$ - 1 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 6 $\Omega$ |       | 230   | 345   | ns   |  |
| Fall Time                                     | t <sub>f</sub>      |   |       | 155   | 235   |      |  |
| Source-Drain Reverse Recovery Time            | t <sub>rr</sub>     | r I <sub>F</sub> = - 1.7 A, dl/dt = 100 A/μs              |       | 128   | 200   |      |  |

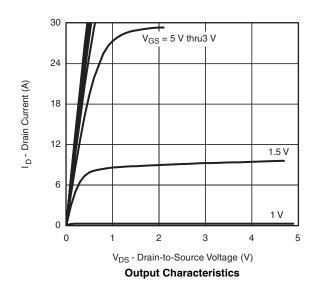
Notes:

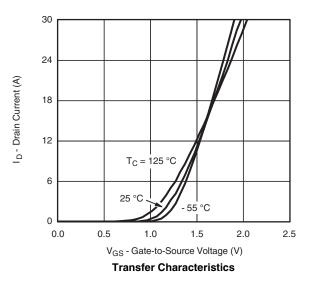
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

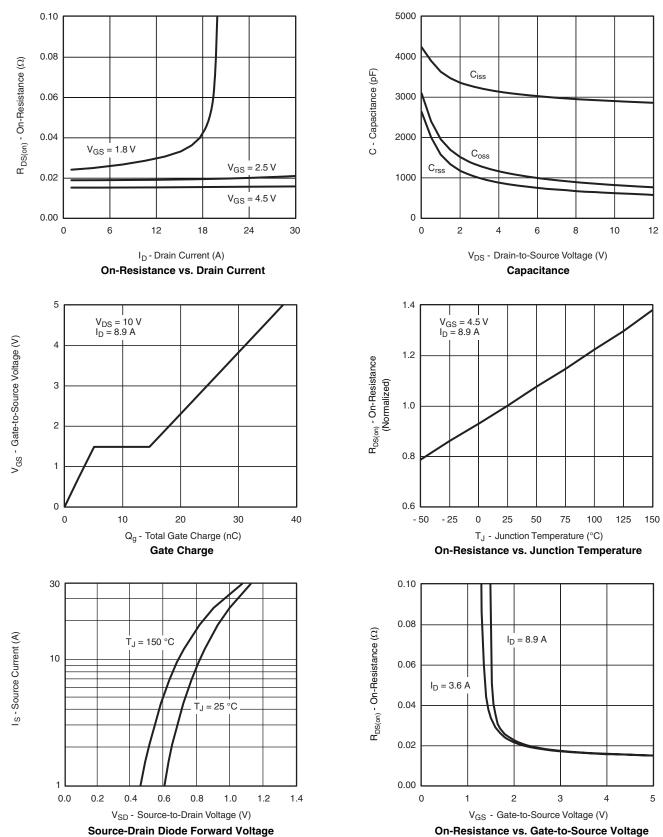




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#### TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





600

#### 0.4 30 0.3 24 $I_D = 350 \ \mu A$ V<sub>GS(th)</sub> Variance (V) 0.2 18 Power (W) 0.1 12 0.0 6 - 0.1 - 0.2 0 - 50 - 25 0 25 50 75 100 125 150 10-2 10-1 10 100 1 T<sub>J</sub> - Temperature (°C) Time (s) **Threshold Voltage** Single Pulse Power 100 Limited by R<sub>DS(on)</sub> IDM Limited 10 P(t) = 0.001I<sub>D</sub> - Drain Current (A) P(t) = 0.01Limited 1 P(t) = 0.1P(t) = 1P(t) = 10T<sub>A</sub> = 25 °C 0.1 Single Pulse DC ∄ +++++ **BVDSS** Limited <u>\_\_</u>\_\_\_[] 0.01 0.1 10 100 1 $V_{DS}$ - Drain-to-Source Voltage (V) \* $V_{DS}$ > minimum $V_{GS}$ at which $R_{DS(on)}$ is specified Safe Operating Area, Junction-to-Ambient 2 1 Normalized Effective Transient Thermal Impedance Duty Cycle = 0.5 0.2 Notes 4 0.1 P<sub>DM</sub> 0.1 0.05 $t_1$ Ĥ₽ t2 t<sub>1</sub> 1. Duty Cycle, D = 0.02 t<sub>2</sub> 2. Per Unit Base = R<sub>thJA</sub> = 80 °C/W 3. $T_{JM}$ - $T_A = P_{DM}Z_{thJA}^{(t)}$ Single Pulse 4. Surface Mounted 1114 T 0.01 10-4 10<sup>-3</sup> 10-2 10-1 10 100 1 Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Ambient

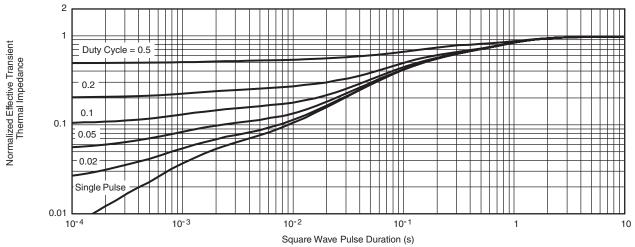
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服务热线:400-655-8788

600



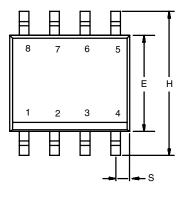
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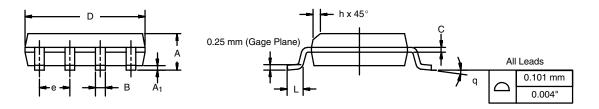


Normalized Thermal Transient Impedance, Junction-to-Foot



## SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

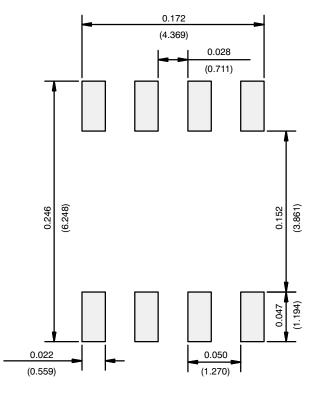




|   | MILLIM | IETERS | INCHES    |       |  |  |
|---|--------|--------|-----------|-------|--|--|
| DIM   | Min    | Мах    | Min       | Max   |  |  |
| A   | 1.35   | 1.75   | 0.053     | 0.069 |  |  |
| A <sub>1</sub>                              | 0.10   | 0.20   | 0.004     | 0.008 |  |  |
| В   | 0.35   | 0.51   | 0.014     | 0.020 |  |  |
| С   | 0.19   | 0.25   | 0.0075    | 0.010 |  |  |
| D   | 4.80   | 5.00   | 0.189     | 0.196 |  |  |
| E   | 3.80   | 4.00   | 0.150     | 0.157 |  |  |
| е   | 1.27   | BSC    | 0.050 BSC |       |  |  |
| н   | 5.80   | 6.20   | 0.228     | 0.244 |  |  |
| h   | 0.25   | 0.50   | 0.010     | 0.020 |  |  |
| L   | 0.50   | 0.93   | 0.020     | 0.037 |  |  |
| q   | 0°     | 8°     | 0°        | 8°    |  |  |
| S   | 0.44   | 0.64   | 0.018     | 0.026 |  |  |
| ECN: C-06527-Rev. I, 11-Sep-06<br>DWG: 5498 |        |        |           |       |  |  |



#### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



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